

ZXMD63N03X

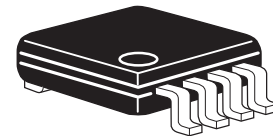
DUAL 30V N-CANNEL ENHANCEMENT MODE MOSFET

SUMMARY

$V_{(BR)DSS}=30V$; $R_{DS(ON)}=0.135\Omega$; $I_D=2.3A$

DESCRIPTION

This new generation of high density MOSFETs from Zetex utilizes a unique structure that combines the benefits of low on-resistance with fast switching speed. This makes them ideal for high efficiency, low voltage, power management applications.



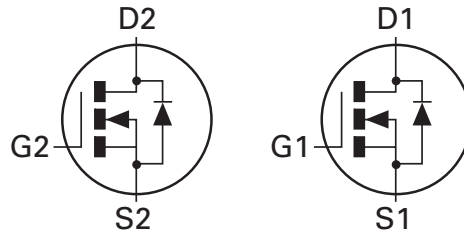
MSOP8

FEATURES

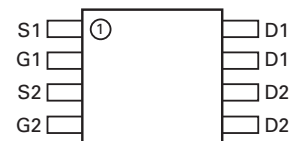
- Low on-resistance
- Fast switching speed
- Low threshold
- Low gate drive
- Low profile SOIC package

APPLICATIONS

- DC - DC converters
- Power management functions
- Disconnect switches
- Motor control



Pin-out



Top view

ORDERING INFORMATION

DEVICE	REEL SIZE (inches)	TAPE WIDTH (mm)	QUANTITY PER REEL
ZXM63N03NXTA	7	12 embossed	1,000
ZXM63N03NXTC	13	12 embossed	4,000

DEVICE MARKING

ZXM63N03

ZXMD63N03X

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DSS}	30	V
Gate- Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($V_{GS}=4.5V$; $T_A=25^\circ C$)(b)(d) ($V_{GS}=4.5V$; $T_A=70^\circ C$)(b)(d)	I_D	2.3 1.8	A
Pulsed Drain Current (c)(d)	I_{DM}	14	A
Continuous Source Current (Body Diode)(b)(d)	I_S	1.5	A
Pulsed Source Current (Body Diode)(c)(d)	I_{SM}	14	A
Power Dissipation at $T_A=25^\circ C$ (a)(d) Linear Derating Factor	P_D	0.87 6.9	W mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ (a)(e) Linear Derating Factor	P_D	1.04 8.3	W mW/ $^\circ C$
Power Dissipation at $T_A=25^\circ C$ (b)(d) Linear Derating Factor	P_D	1.25 10	W mW/ $^\circ C$
Operating and Storage Temperature Range	$T_j; T_{stg}$	-55 to +150	$^\circ C$

THERMAL RESISTANCE

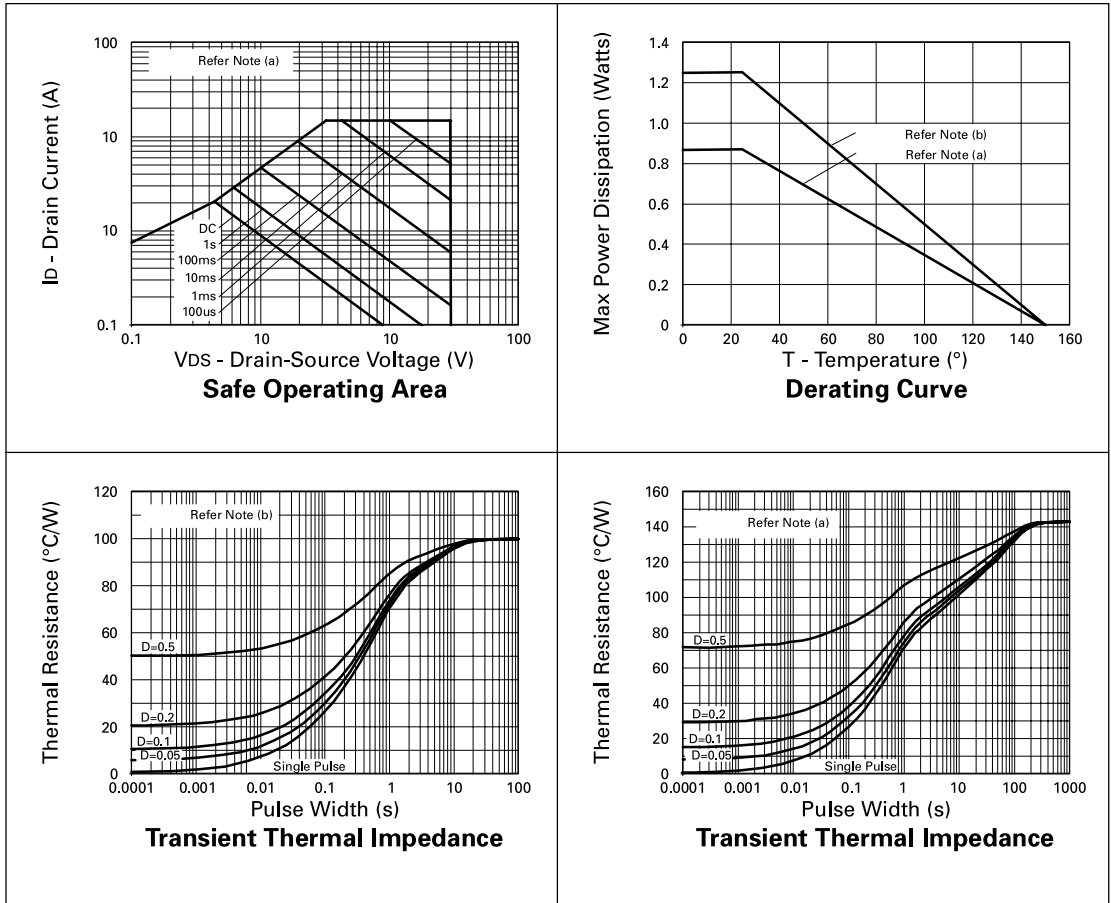
PARAMETER	SYMBOL	VALUE	UNIT
Junction to Ambient (a)(d)	$R_{\theta JA}$	143	$^\circ C/W$
Junction to Ambient (b)(d)	$R_{\theta JA}$	100	$^\circ C/W$
Junction to Ambient (a)(e)	$R_{\theta JA}$	120	$^\circ C/W$

NOTES:

- (a) For a device surface mounted on 25mm x 25mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions
- (b) For a device surface mounted on FR4 PCB measured at $t \leq 10$ secs.
- (c) Repetitive rating - pulse width limited by maximum junction temperature. Refer to Transient Thermal Impedance graph.
- (d) For device with one active die.
- (e) For device with two active die running at equal power.

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CHARACTERISTICS



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ELECTRICAL CHARACTERISTICS (at $T_{amb} = 25^{\circ}\text{C}$ unless otherwise stated)

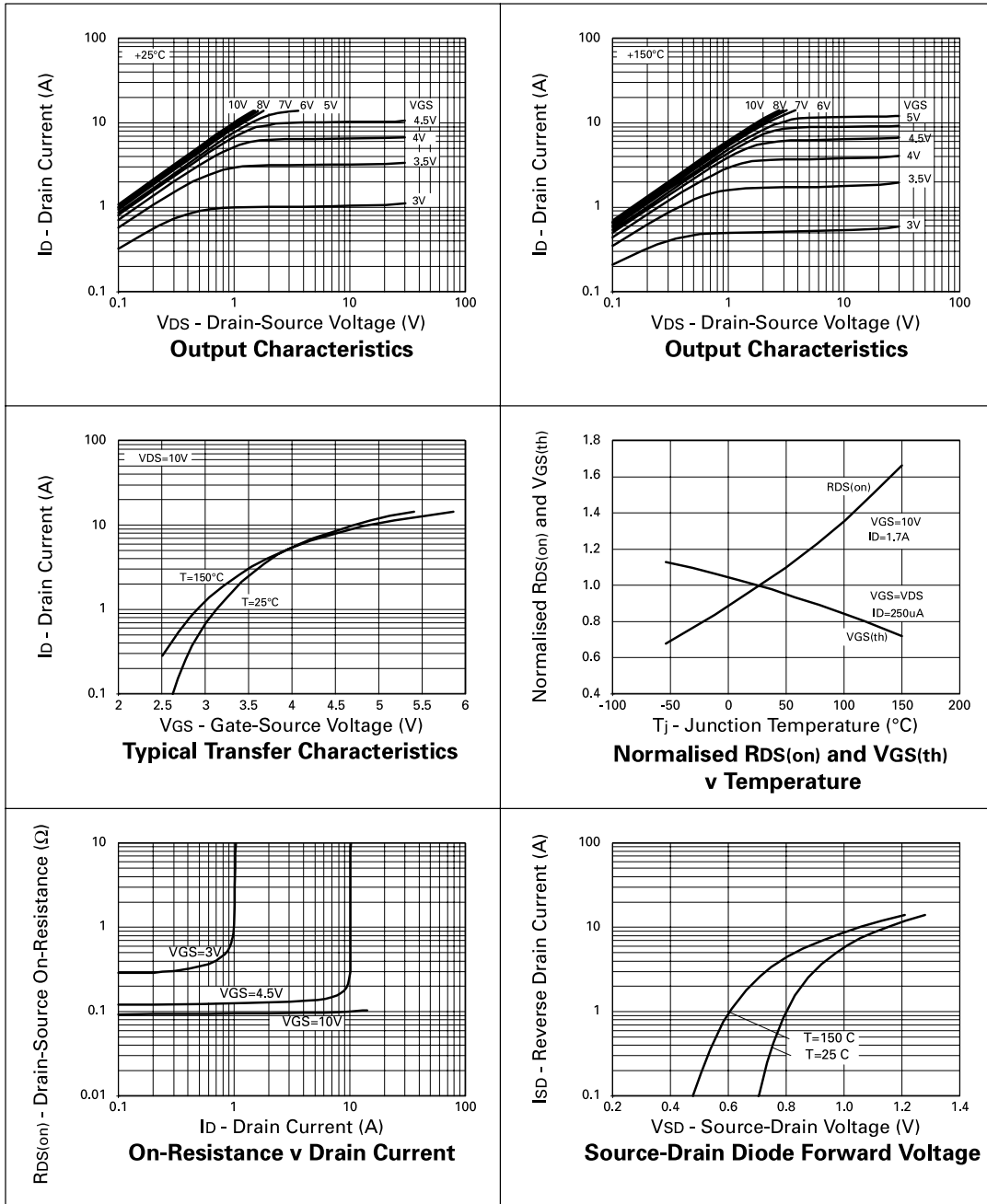
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	CONDITIONS
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	30			V	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$
Zero Gate Voltage Drain Current	I_{DSS}			1	μA	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$
Gate-Body Leakage	I_{GSS}			100	nA	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$
Gate-Source Threshold Voltage	$V_{GS(th)}$	1.0			V	$I_D=250\mu\text{A}$, $V_{DS}=V_{GS}$
Static Drain-Source On-State Resistance (1)	$R_{DS(on)}$			0.135 0.200	Ω Ω	$V_{GS}=10\text{V}$, $I_D=1.7\text{A}$ $V_{GS}=4.5\text{V}$, $I_D=0.85\text{A}$
Forward Transconductance (3)	g_{fs}	1.9			S	$V_{DS}=10\text{V}$, $I_D=0.85\text{A}$
DYNAMIC (3)						
Input Capacitance	C_{iss}		290		pF	$V_{DS}=25\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$
Output Capacitance	C_{oss}		70		pF	
Reverse Transfer Capacitance	C_{rss}		20		pF	
SWITCHING (2) (3)						
Turn-On Delay Time	$t_{d(on)}$		2.5		ns	$V_{DD}=15\text{V}$, $I_D=1.7\text{A}$ $R_G=6.1\Omega$, $R_D=8.7\Omega$ (Refer to test circuit)
Rise Time	t_r		4.1		ns	
Turn-Off Delay Time	$t_{d(off)}$		9.6		ns	
Fall Time	t_f		4.4		ns	
Total Gate Charge	Q_g			8	nC	$V_{DS}=24\text{V}$, $V_{GS}=10\text{V}$, $I_D=1.7\text{A}$ (Refer to test circuit)
Gate-Source Charge	Q_{gs}			1.2	nC	
Gate Drain Charge	Q_{gd}			2	nC	
SOURCE-DRAIN DIODE						
Diode Forward Voltage (1)	V_{SD}			0.95	V	$T_j=25^{\circ}\text{C}$, $I_S=1.7\text{A}$, $V_{GS}=0\text{V}$
Reverse Recovery Time (3)	t_{rr}		16.9		ns	$T_j=25^{\circ}\text{C}$, $I_F=1.7\text{A}$, $di/dt=100\text{A}/\mu\text{s}$
Reverse Recovery Charge(3)	Q_{rr}		9.5		nC	

NOTES:

- (1) Measured under pulsed conditions. Width=300 μs . Duty cycle @2% .
- (2) Switching characteristics are independent of operating junction temperature.
- (3) For design aid only, not subject to production testing.

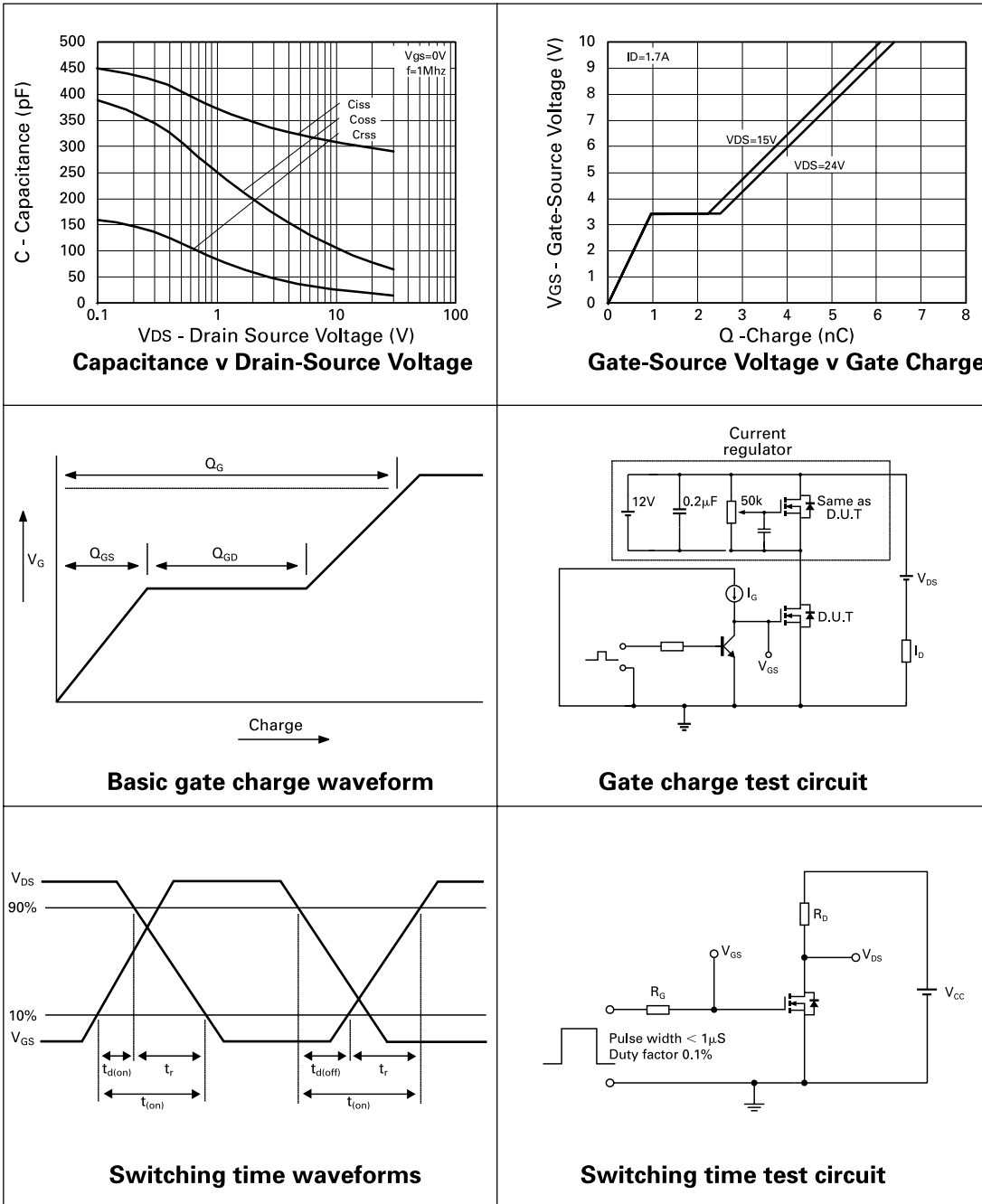
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TYPICAL CHARACTERISTICS



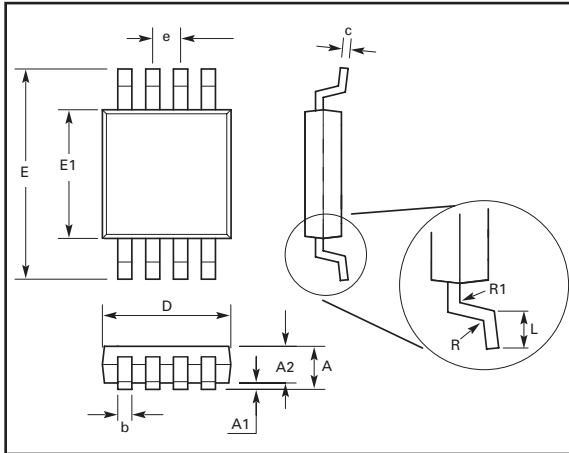
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TYPICAL CHARACTERISTICS

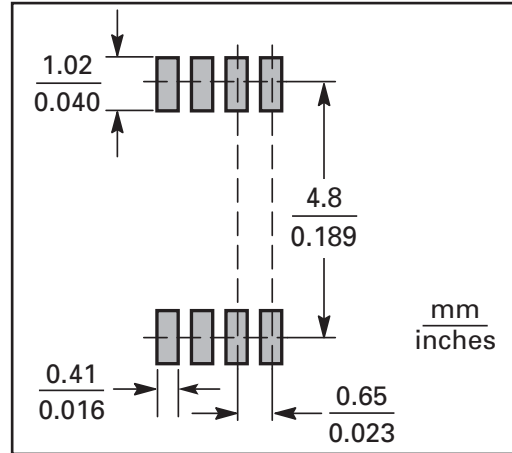


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PACKAGE DETAILS



PAD LAYOUT DETAILS



PACKAGE DIMENSIONS

DIM	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	0.91	1.11	0.036	0.044
A1	0.10	0.20	0.004	0.008
B	0.25	0.36	0.010	0.014
C	0.13	0.18	0.005	0.007
D	2.95	3.05	0.116	0.120
e	0.65NOM		0.0256	
e1	0.33NOM		0.0128	
E	2.95	3.05	0.116	0.120
H	4.78	5.03	0.188	0.198
L	0.41	0.66	0.016	0.026
θ°	0°	6°	0°	6°

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